

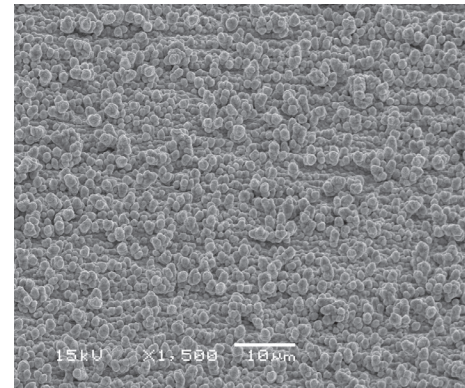
Reverse treat, superior adhesion, electrodeposited copper foil.

**Applications:**

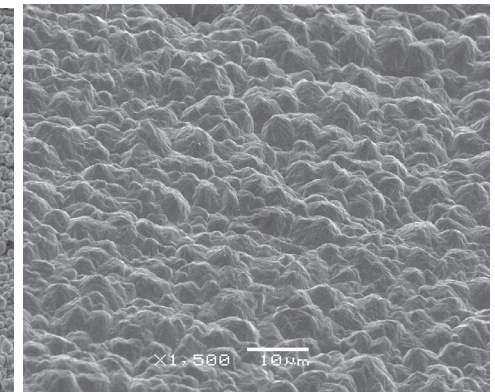
- PCB inner layers

**Features:**

- IPC Grade III
- Increased roughening treatment on drum side of foil
- Excellent adhesion to a wide range of resin systems



Treated Drum Side  
H oz. /18 µm (1500x)



Untreated Matte Side  
H oz. /18 µm (1500x)

**Typical Values:**

| Attribute                             |            | Unit                  | Value |      |      | Reference   |
|---------------------------------------|------------|-----------------------|-------|------|------|---|
| Thickness Designation                 |            |                       | H     | 1    | 2    | IPC-4562,<br>1.2.5.1<br>Table 1-1;<br>IPC-TM-650-2.2.12 |
| Nominal Thickness                     |            | µm                    | 18    | 35   | 70   |   |
|                                       |            | oz.                   | 1/2   | 1    | 2    |   |
| Area Weight                           |            | g/m <sup>2</sup>      | 152.5 | 305  | 610  |   |
|                                       |            | g/254 in <sup>2</sup> | 25    | 50   | 100  |   |
|                                       |            | oz./ft <sup>2</sup>   | 0.5   | 1    | 2    |   |
| Roughness                             | Drum Side  | µm                    | 3.6   |      |      | IPC-TM-650-2.2.17                                       |
|                                       |            | µ"                    | 140   |      |      |   |
|                                       | Matte Side | µm                    | 4.5   | 5.7  | 8.9  |   |
|                                       |            | µ"                    | 175   | 225  | 350  |   |
| Tensile                               | Ambient    | Kg/mm <sup>2</sup>    | 42.2  | 38.7 | 36.9 | IPC-TM-650-2.4.18                                       |
|                                       |            | Kpsi                  | 60    | 55   | 52.5 |   |
|                                       | 180°C      | Kg/mm <sup>2</sup>    | 21    |      |      |   |
|                                       |            | Kpsi                  | 30    |      |      |   |
| Elongation                            | Ambient    | %                     | 8     | 15   | 20   |   |
|                                       | 180°C      | %                     | 8     |      |      |   |
| Peel Strength*<br>(Drum/Treated Side) | Cond. B    | Kg/cm                 | 1.07  | 1.42 | 1.96 | IPC-TM-650-2.4.8  |
|                                       |            | Lbs/in                | 6.0   | 8.0  | 11.0 |   |

\* Peel strength measured on 170°C Tg Epoxy

Information in this document is believed to be accurate and reliable and is for informational purpose only. This data sheet does not create any warranties, expressed or implied, as to the fitness for any particular purpose or use. The Denkai America Inc. name and logo are registered trademarks of Nippon Denkai, Ltd. © 2020, Denkai America Inc. All rights reserved. Rev May 4, 2020